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Renesas Technology Corp.
Customer Support Dept.
April 1, 2003

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TBB1008

Twin Build in Biasing Circuit MOS FET IC
VHF/UHF RF Amplifier

ADE-208-1599 (Z)

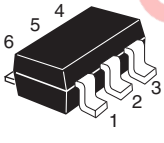
Rev.0
Jun. 2002

Features

- Small SMD package CMPAK-6 built in twin BBFET; To reduce using parts cost & PC board space.
- Suitable for World Standard Tuner RF amplifier.
- Very useful for total tuner cost reduction.
- Withstanding to ESD; Build in ESD absorbing diode. Withstand up to 200 V at C = 200 pF, Rs = 0 conditions.
- Provide mini mold packages; CMPAK-6

Outline

CMPAK-6



1. Gate-1(1)
2. Source
3. Drain(1)
4. Drain(2)
5. Gate-2
6. Gate-1(2)

Notes:
1. Marking is “HM”.
2. TBB1008 is individual type number of HITACHI TWIN BBFET.

Absolute Maximum Ratings

(Ta = 25°C)

Item	Symbol	Ratings	Unit
Drain to source voltage	V_{DS}	6	V
Gate1 to source voltage	V_{G1S}	+6 -0	V
Gate2 to source voltage	V_{G2S}	+6 -0	V
Drain current	I_D	30	mA
Channel power dissipation	Pch[*3]	250	mW
Channel temperature	Tch	150	°C
Storage temperature	Tstg	–55 to +150	°C

Notes: 3. Value on the glass epoxy board (50 mm × 40 mm × 1 mm).

Electrical Characteristics

The below specification are applicable for UHF unit (FET1)

(Ta = 25°C)

Item	Symbol	Min	Typ	Max	Unit	Test Conditions
Drain to source breakdown voltage	$V_{(BR)DSS}$	6	—	—	V	I_D = 200 µA, V_{G1S} = V_{G2S} = 0
Gate1 to source breakdown voltage	$V_{(BR)G1SS}$	+6	—	—	V	I_{G1} = +10 µA, V_{G2S} = V_{DS} = 0
Gate2 to source breakdown voltage	$V_{(BR)G2SS}$	+6	—	—	V	I_{G2} = +10 µA, V_{G1S} = V_{DS} = 0
Gate1 to source cutoff current	I_{G1SS}	—	—	+100	nA	V_{G1S} = +5 V, V_{G2S} = V_{DS} = 0
Gate2 to source cutoff current	I_{G2SS}	—	—	+100	nA	V_{G2S} = +5 V, V_{G1S} = V_{DS} = 0
Gate1 to source cutoff voltage	$V_{G1S(off)}$	0.5	0.7	1.0	V	V_{DS} = 5 V, V_{G2S} = 4 V, I_D = 100 µA
Gate2 to source cutoff voltage	$V_{G2S(off)}$	0.5	0.7	1.0	V	V_{DS} = 5 V, V_{G1S} = 5 V, I_D = 100 µA
Drain current	$I_{D(op)}$	13	17	21	mA	V_{DS} = 5 V, V_{G1} = 5 V V_{G2S} = 4 V, R_G = 100 kΩ
Forward transfer admittance	$\|y_{fs}\|$	21	26	32	mS	V_{DS} = 5 V, V_{G1} = 5 V, V_{G2S} = 4 V R_G = 100 kΩ, f = 1 kHz
Input capacitance	Ciss	1.4	1.8	2.2	pF	V_{DS} = 5 V, V_{G1} = 5 V
Output capacitance	Coss	1.0	1.4	1.8	pF	V_{G2S} =4 V, R_G = 100 kΩ
Reverse transfer capacitance	Crss	—	0.02	0.04	pF	f = 1 MHz
Power gain	PG	16	21	—	dB	V_{DS} = V_{G1} = 5 V, V_{G2S} = 4 V R_G = 100 kΩ, f = 900 MHz Zi = S11*, Zo = S22* (:PG)
Noise figure	NF	—	1.7	2.5	dB	Zi = S11opt (:NF)

The below specification are applicable for VHF unit (FET2)

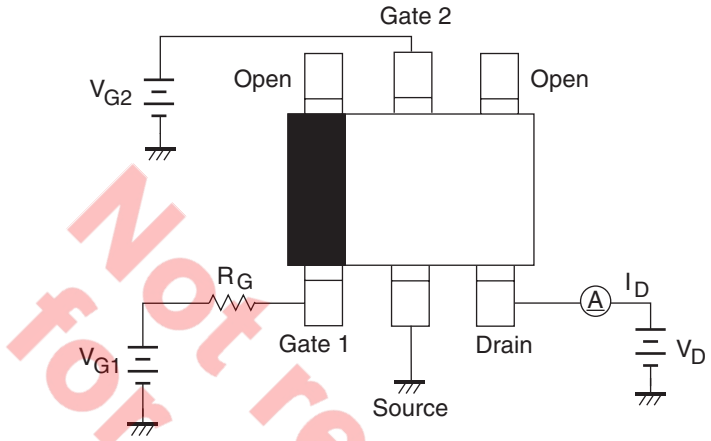
(Ta = 25°C)

Item	Symbol	Min	Typ	Max	Unit	Test Conditions
Drain to source breakdown voltage	$V_{(BR)DSS}$	6	—	—	V	I_D = 200 µA, V_{G1S} = V_{G2S} = 0
Gate1 to source breakdown voltage	$V_{(BR)G1SS}$	+6	—	—	V	I_{G1} = +10 µA, V_{G2S} = V_{DS} = 0
Gate2 to source breakdown voltage	$V_{(BR)G2SS}$	+6	—	—	V	I_{G2} = +10 µA, V_{G1S} = V_{DS} = 0
Gate1 to source cutoff current	I_{G1SS}	—	—	+100	nA	V_{G1S} = +5 V, V_{G2S} = V_{DS} = 0
Gate2 to source cutoff current	I_{G2SS}	—	—	+100	nA	V_{G2S} = +5 V, V_{G1S} = V_{DS} = 0
Gate1 to source cutoff voltage	$V_{G1S(off)}$	0.5	0.75	1.0	V	V_{DS} = 5 V, V_{G2S} = 4 V, I_D = 100 µA
Gate2 to source cutoff voltage	$V_{G2S(off)}$	0.5	0.75	1.0	V	V_{DS} = 5 V, V_{G1S} = 5 V, I_D = 100 µA
Drain current	$I_{D(op)}$	16	20	24	mA	V_{DS} = 5 V, V_{G1} = 5 V, V_{G2S} = 4 V R_G = 100 kΩ
Forward transfer admittance	$\|y_{fs}\|$	27	32	38	mS	V_{DS} = 5 V, V_{G1} = 5 V, V_{G2S} =4 V R_G = 100 kΩ, f = 1 kHz
Input capacitance	Ciss	2.3	2.7	3.1	pF	V_{DS} = 5 V, V_{G1} = 5 V
Output capacitance	Coss	1.4	1.8	2.2	pF	V_{G2S} =4 V, R_G = 100 kΩ
Reverse transfer capacitance	Crss	—	0.03	0.05	pF	f = 1 MHz
Power gain	PG	24	29	—	dB	V_{DS} = V_{G1} = 5 V, V_{G2S} = 4 V
Noise figure	NF	—	1.2	1.7	dB	R_G = 100 kΩ, f = 200 MHz

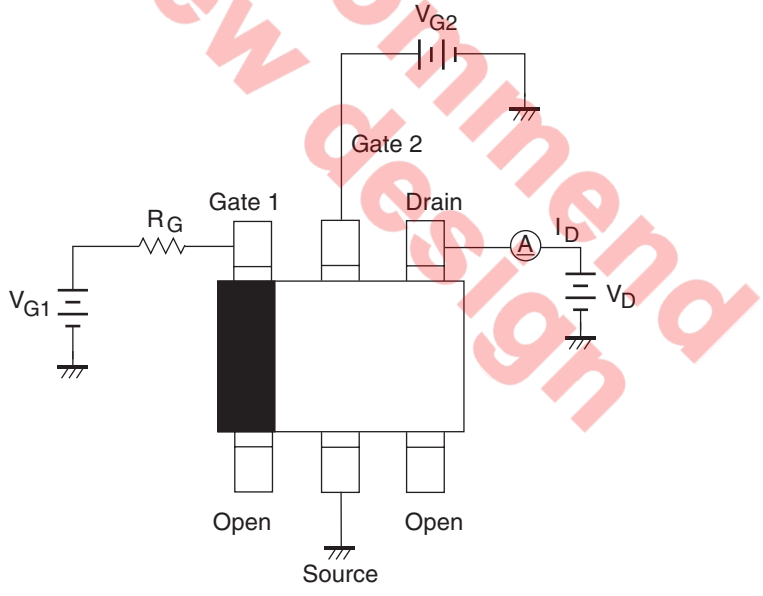
Test Circuits

• **DC Biasing Circuit for Operating Characteristic Items** ($I_{D(op)}$, lyfsl, Ciss, Coss, Crss, NF, PG)

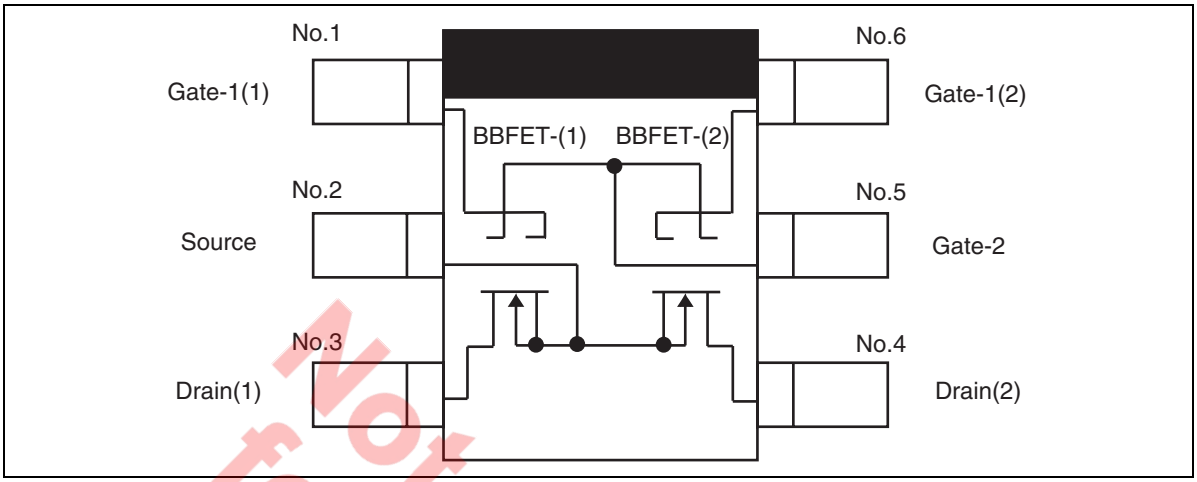
• Measurment of FET1



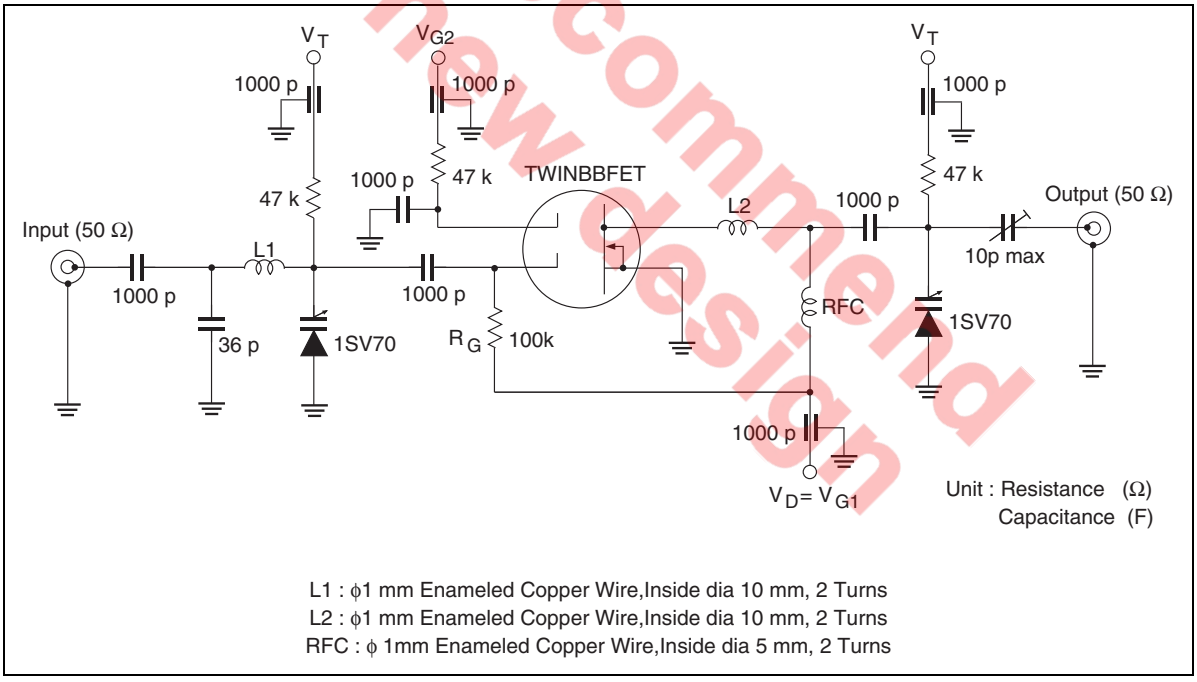
• Measurment of FET2



• **Equivalent Circuit**

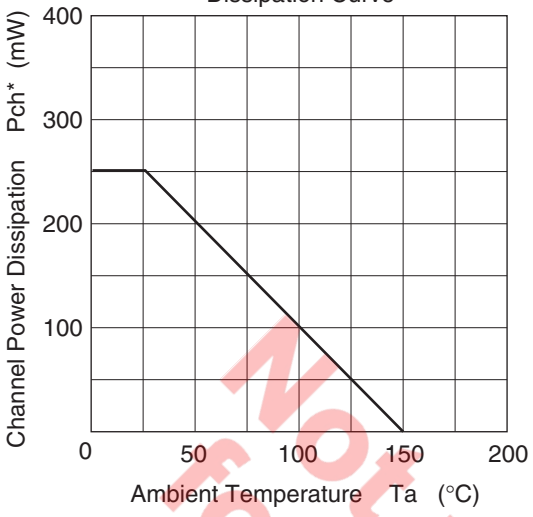


• **200 MHz Power Gain, Noise Figure Test Circuit**



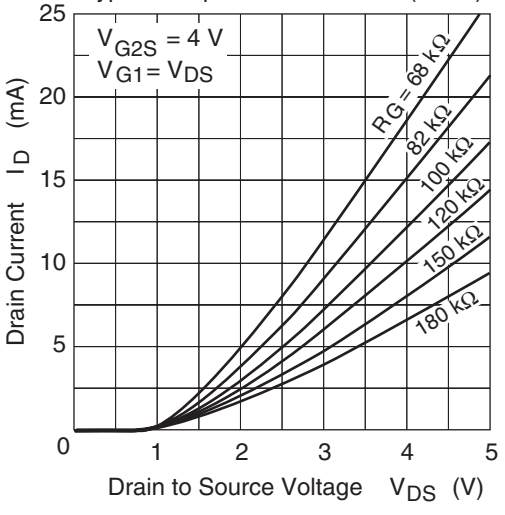
L1 : ϕ1 mm Enameled Copper Wire,Inside dia 10 mm, 2 Turns
L2 : ϕ1 mm Enameled Copper Wire,Inside dia 10 mm, 2 Turns
RFC : ϕ 1mm Enameled Copper Wire,Inside dia 5 mm, 2 Turns

Maximum Channel Power Dissipation Curve

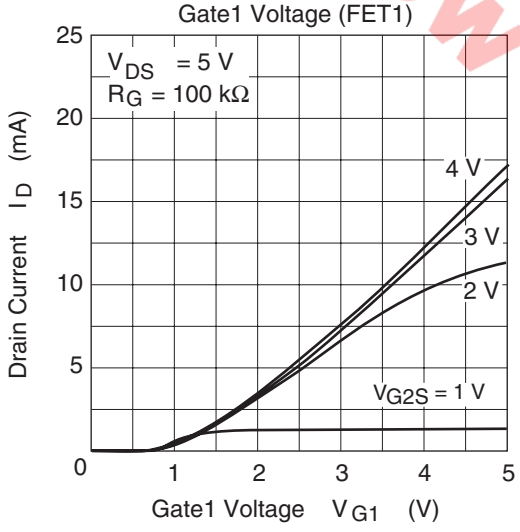


* Value on the glass epoxy board (50mm × 40mm × 1mm)

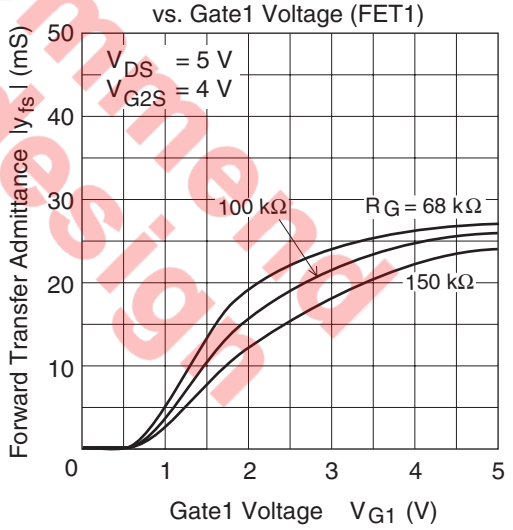
Typical Output Characteristics (FET1)



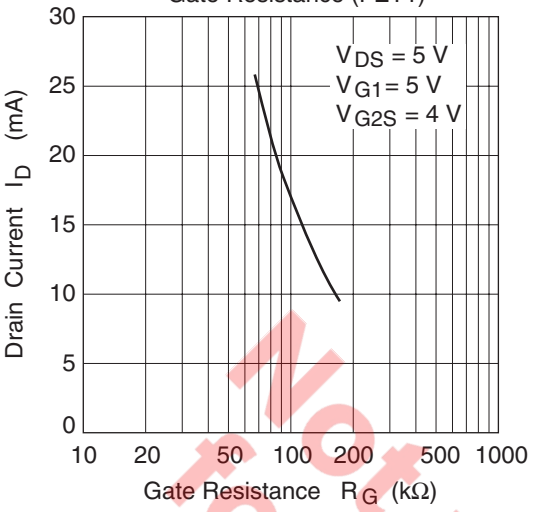
Drain Current vs. Gate1 Voltage (FET1)



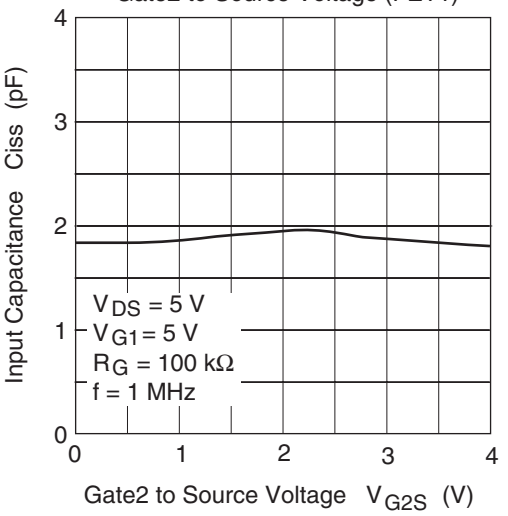
Forward Transfer Admittance vs. Gate1 Voltage (FET1)



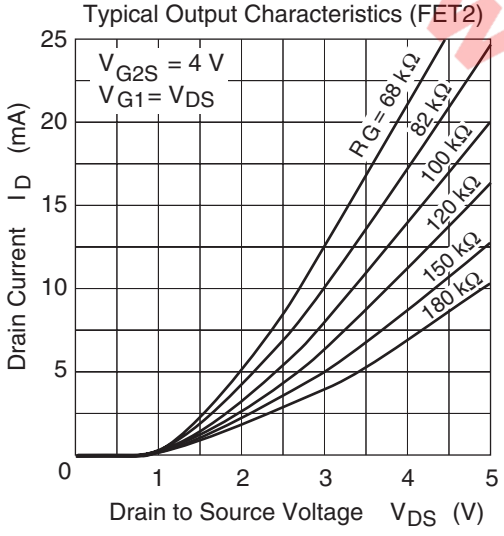
Drain Current vs.
Gate Resistance (FET1)



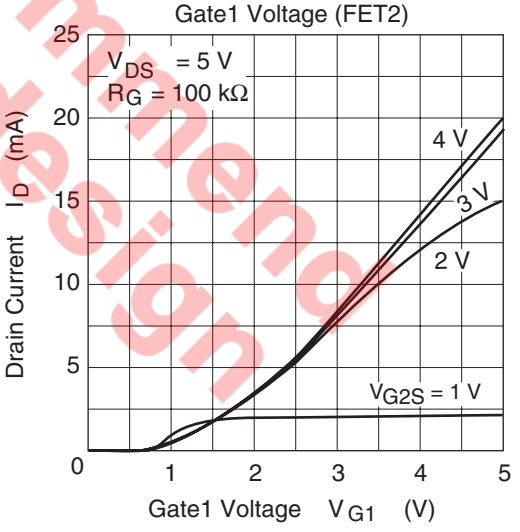
Input Capacitance vs.
Gate2 to Source Voltage (FET1)

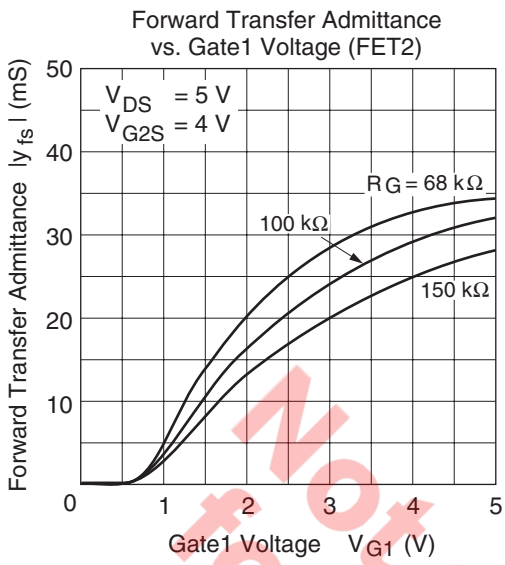


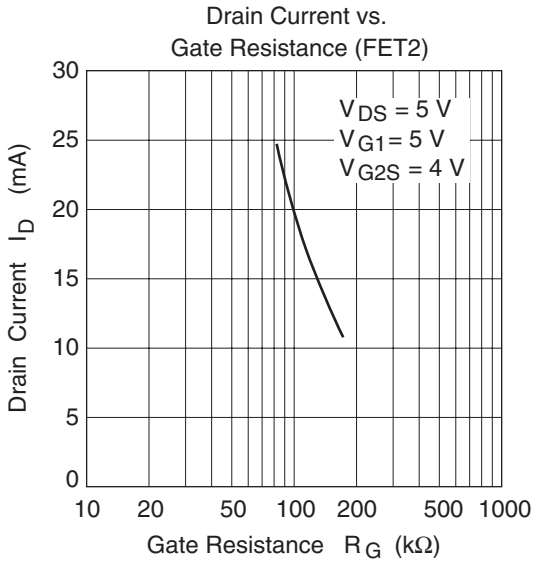
Typical Output Characteristics (FET2)

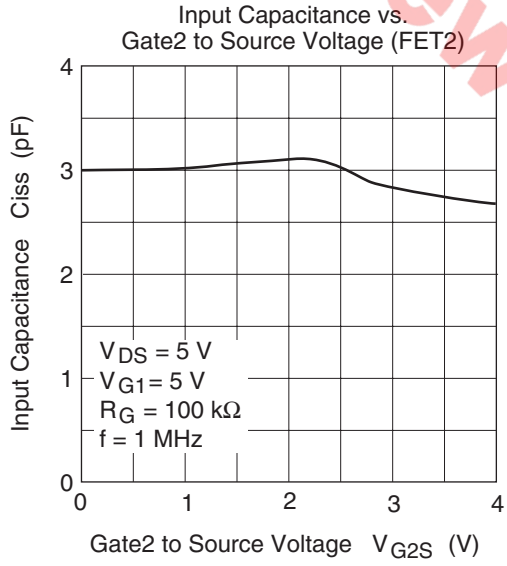


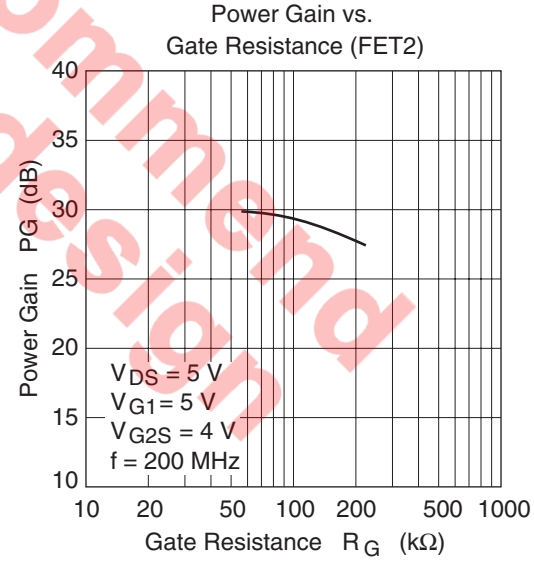
Drain Current vs.
Gate1 Voltage (FET2)

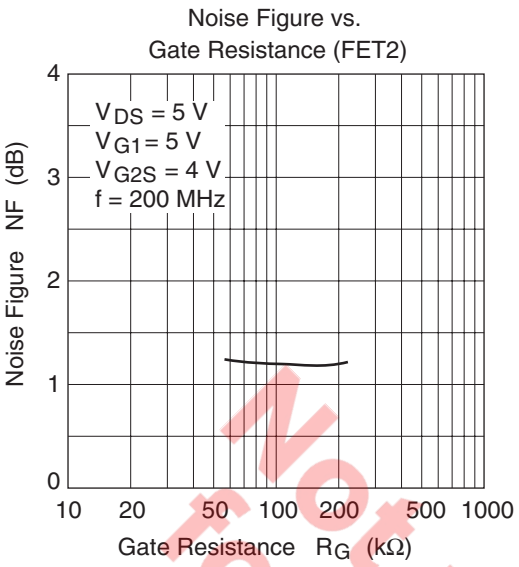


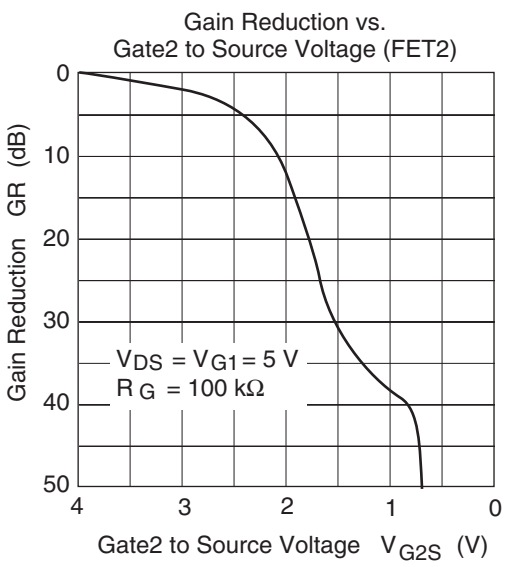






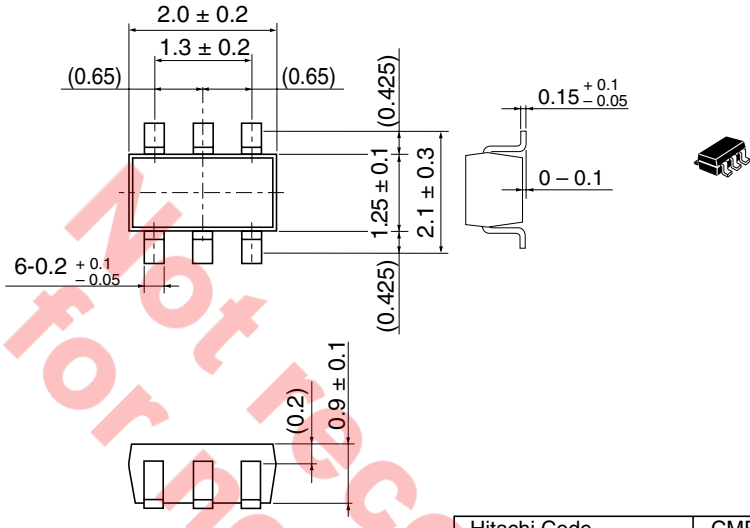






Package Dimensions

As of January, 2002
Unit: mm



Hitachi Code	CMPAK-6
JEDEC	—
JEITA	Conforms
Mass (reference value)	0.006 g

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